



# 2A, 200V - 1000V Fast Recovery Surface Mount Rectifier

## **FEATURES**

- Glass passivated chip junction
- Ideal for automated placement
- Low power loss, high efficiency
- · Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

## **APPLICATIONS**

- DC to DC converter
- Switching mode converters and inverters
- · General purpose

## **MECHANICAL DATA**

· Case: Thin SMA

Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

• Meet JESD 201 class 2 whisker test

Polarity: Indicated by cathode band

• Weight: 0.029g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	2	Α	
$V_{RRM}$	200 - 1000	٧	
I <sub>FSM</sub>	50	Α	
T <sub>J MAX</sub>	150	°C	
Package	Thin SMA		
Configuration	Single die		









ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS2DAL	RS2GAL	RS2JAL	RS2KAL	RS2MAL	UNIT
Marking code on the devi	ce		RS2DAL	RS2GAL	RS2JAL	RS2KAL	RS2MAL	
Repetitive peak reverse v	Repetitive peak reverse voltage		200	400	600	800	1000	V
Reverse voltage, total rms value		$V_{R(RMS)}$	140	280	420	560	700	٧
Forward current		I <sub>F</sub>	2				Α	
Surge peak forward current single half sine	t = 8.3ms	I			50			Α
wave superimposed on rated load $t = 1.0 ms$		I <sub>FSM</sub>	140				Α	
Junction temperature T <sub>J</sub>		$T_J$	-55 to +150			°C		
Storage temperature T <sub>STG</sub>		T <sub>STG</sub>	-55 to +150				°C	



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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	16	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	73	°C/W	
Junction-to-case thermal resistance	R <sub>eJC</sub>	14	°C/W	

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
		I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C		0.93	-	V
	RS2DAL	I <sub>F</sub> = 2.0A, T <sub>J</sub> = 25°C		1.01	1.30	V
	RS2GAL RS2JAL	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.78	-	V
<b>F</b> (1)		I <sub>F</sub> = 2.0A, T <sub>J</sub> = 125°C	.,	0.88	1.02	V
Forward voltage <sup>(1)</sup>		I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C	$V_F$	0.98	-	V
	RS2KAL	I <sub>F</sub> = 2.0A, T <sub>J</sub> = 25°C		1.06	1.30	V
	RS2MAL	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.83	-	V
		I <sub>F</sub> = 2.0A, T <sub>J</sub> = 125°C		0.93	1.05	V
- (2)		T <sub>J</sub> = 25°C		-	1	μΑ
Reverse current @ rated V	R <sup>'-'</sup>	T <sub>J</sub> = 125°C	l <sub>R</sub>	-	40	μΑ
	RS2DAL RS2GAL		t <sub>rr</sub>	-	150	ns
Reverse recovery time	RS2JAL	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$		-	250	ns
	RS2KAL RS2MAL			-	500	ns
Junction capacitance	RS2DAL RS2GAL RS2JAL	1MHz, V <sub>B</sub> = 4.0V	CO	11	-	pF
	RS2KAL RS2MAL	, 11		10	-	pF

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING		
RS2xAL	Thin SMA	14,000 / Tape & Reel		

## Notes:

1. "x" defines voltage from 200V(RS2DAL) to 1000V(RS2MAL)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

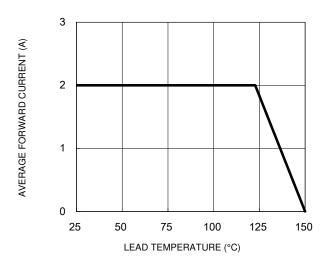


Fig.3 Typical Reverse Characteristics

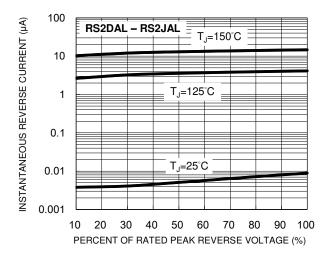


Fig.5 Typical Reverse Characteristics

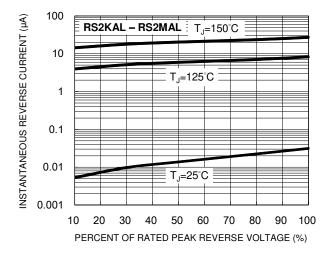
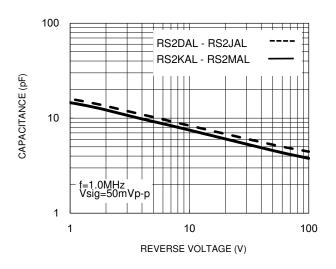
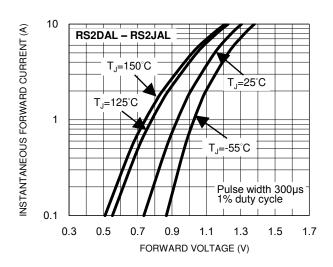


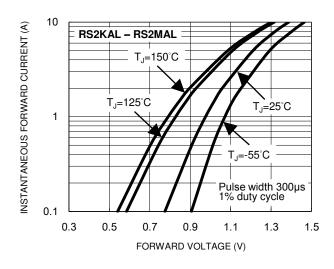
Fig.2 Typical Junction Capacitance



**Fig.4 Typical Forward Characteristics** 



**Fig.6 Typical Forward Characteristics** 

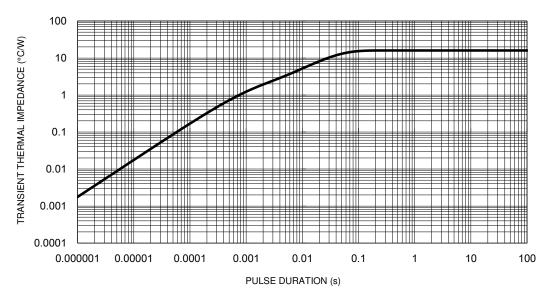


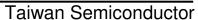
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## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.7 Typical Transient Thermal Impedance

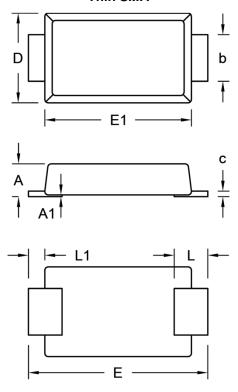






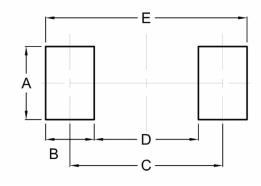
# **PACKAGE OUTLINE DIMENSIONS**

Thin SMA



DIM.	Unit (mm)		Unit (inch)	
Dilvi.	Min.	Max.	Min.	Max.
Α	0.90	1.00	0.035	0.039
A1	0.00	0.10	0.000	0.004
b	1.25	1.45	0.049	0.057
С	0.10	0.22	0.004	0.009
D	2.50	2.70	0.098	0.106
E	5.05	5.35	0.199	0.211
E1	4.15	4.35	0.163	0.171
L	0.75	1.20	0.030	0.047
L1	0.30	0.60	0.012	0.024

# **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

# **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code



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